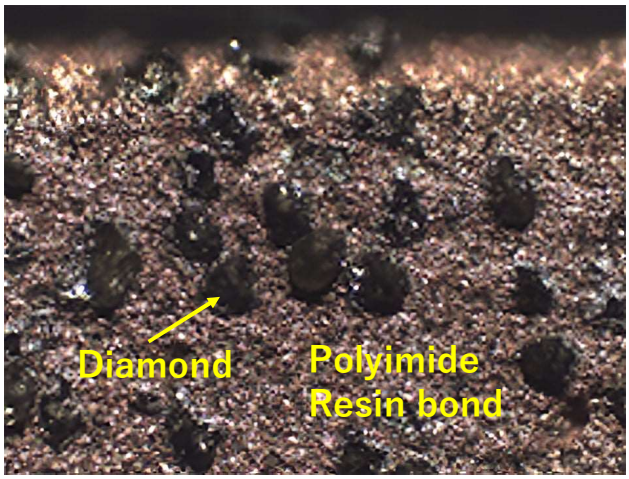
Polyimide Resin Bond

CEPLAX® BLADE

Our unique polyimide resin bond blade developed to suit various work materials.
Thermal degradation is minimized by the use of polyimide, a super heat-resistant resin in the bond.
Polyimide resin is extremely rigid and therefore has excellent wear resistance and shape retention.



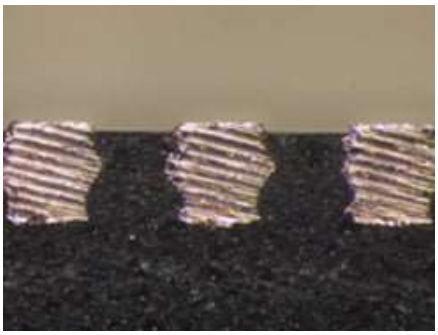
Applications

CSP substrates / Glass, etc. / CMOS substrates / Ceramics / Tungsten carbide, etc.

Features

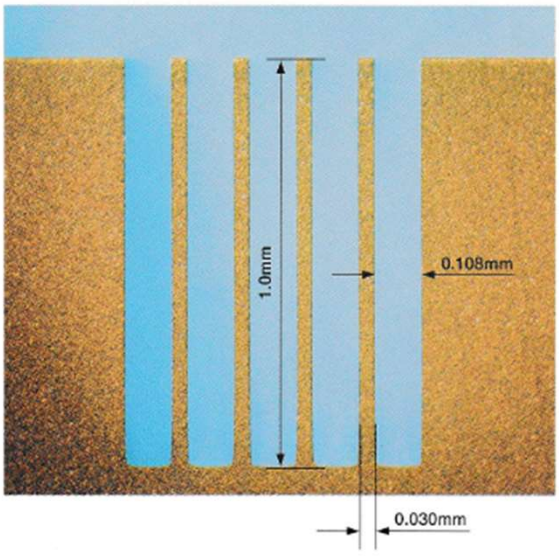
Chipping reduction / Ultra grindability

QFN Dicing with CEPLAX BLADE



Key points in cutting: the lead is characterized by the absence of terminals at the periphery, and it is important to control the burr (distance between terminals) of the copper that is the terminal on the cut surface.

Fine grooving on Tungsten Carbide Metal



EX. : SD600-25-CX48 56D/0.1T/40H						
Abrasive type	Grit	Concent	Bond	OD	Thick	ID
SD	600	25	CX48	56D	0.1T	40H
SD	#2000	15-125	CX48 (↑HARD)	Φ46mm~ 80mm	0.1~0.5mm	40H
SDC	#1500		CX88			
CBN	#1200		CX4N			
	#1000		CX8N (↓SOFT)			
	#800					
	#600					
	#500					
	#400					
	#325					
	#270					
	#230					

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http://www.uwin-g.co.jp/